

BAS16XV2

Switching Diode

Features

- High-Speed Switching Applications
- Lead Finish: 100% Matte Sn (Tin)
- Qualified Reflow Temperature: 260°C
- Extremely Small SOD-523 Package
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|-----------------|-------|------|
| Continuous Reverse Voltage | V_R | 100 | V |
| Continuous Forward Current | I_F | 200 | mA |
| Peak Forward Surge Current | $I_{FM(surge)}$ | 500 | mA |
| Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%) | I_{FRM} | 500 | mA |
| Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^\circ\text{C}$ prior to surge) | I_{FSM} | | A |
| $t = 1 \mu\text{s}$ | | 4.0 | |
| $t = 1 \text{ ms}$ | | 1.0 | |
| $t = 1 \text{ s}$ | | 0.5 | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

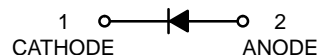
| Characteristic | Symbol | Max | Unit |
|---|-----------------|------------|---------------------------|
| Total Device Dissipation, (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 200 | mW |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 635 | $^\circ\text{C}/\text{W}$ |
| Junction and Storage Temperature | T_J, T_{stg} | -55 to 150 | $^\circ\text{C}$ |

1. FR-5 Minimum Pad.



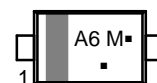
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SOD-523
CASE 502

MARKING DIAGRAM



A6 = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

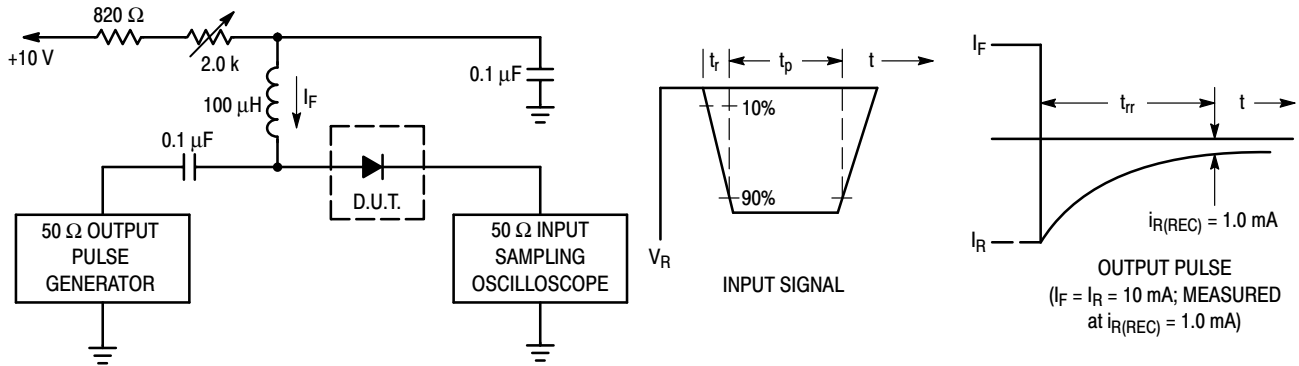
| Device | Package | Shipping† |
|--------------|----------------------|--------------------|
| BAS16XV2T1G | SOD-523 (Pb-Free) | 3000 / Tape & Reel |
| BAS16XV2T5G | SOD-523 (Pb-Free) | 8000 / Tape & Reel |
| SBAS16XV2T1G | SOD-523 (Pb-Free) | 3000 / Tape & Reel |
| SBAS16XV2T5G | SOD-523 (Pb-Free) | 8000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BAS16XV2

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|---|------------|-----|----------------------------|---------------|
| OFF CHARACTERISTICS | | | | |
| Reverse Voltage Leakage Current ($V_R = 100\text{ V}$) ($V_R = 75\text{ V}, T_J = 150^\circ\text{C}$) ($V_R = 25\text{ V}, T_J = 150^\circ\text{C}$) | I_R | – | 1.0 50 30 | μA |
| Reverse Breakdown Voltage ($I_{BR} = 100\ \mu\text{A}$) | $V_{(BR)}$ | 100 | – | V |
| Forward Voltage ($I_F = 1.0\text{ mA}$) ($I_F = 10\text{ mA}$) ($I_F = 50\text{ mA}$) ($I_F = 150\text{ mA}$) | V_F | – | 715 855 1000 1250 | mV |
| Diode Capacitance ($V_R = 0, f = 1.0\text{ MHz}$) | C_D | – | 2.0 | pF |
| Forward Recovery Voltage ($I_F = 10\text{ mA}, t_r = 20\text{ ns}$) | V_{FR} | – | 1.75 | V |
| Reverse Recovery Time ($I_F = I_R = 10\text{ mA}, R_L = 50\ \Omega$) | t_{rr} | – | 6.0 | ns |
| Stored Charge ($I_F = 10\text{ mA}$ to $V_R = 5.0\text{ V}, R_L = 500\ \Omega$) | Q_S | – | 45 | pC |



- Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.
 2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 10 mA.
 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

BAS16XV2

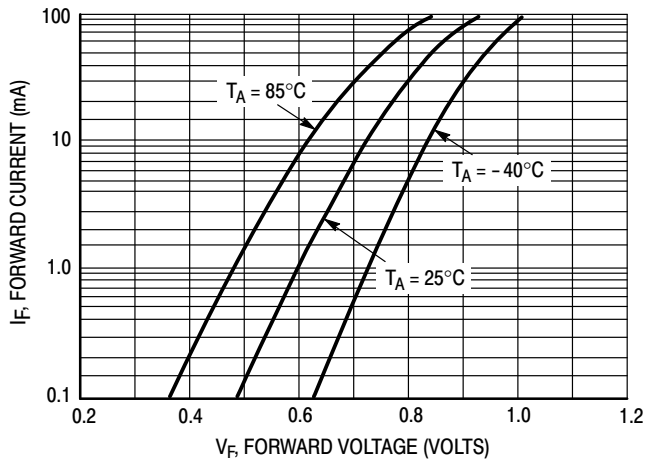


Figure 2. Forward Voltage

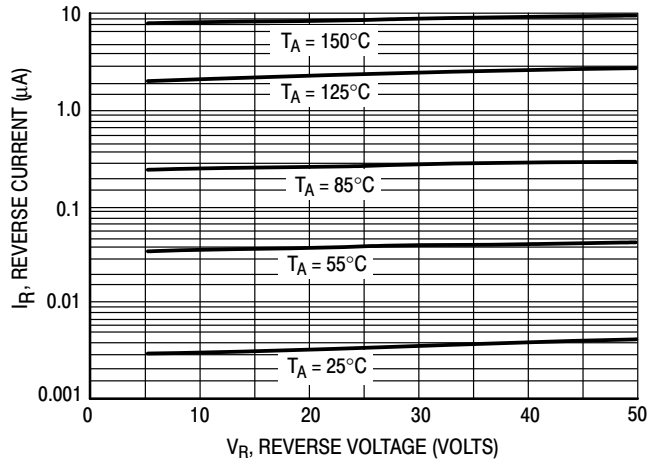


Figure 3. Leakage Current

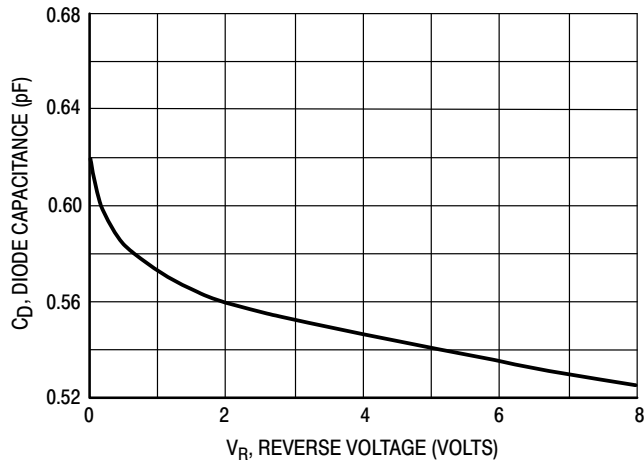
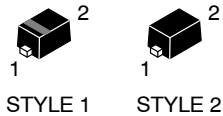


Figure 4. Capacitance

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

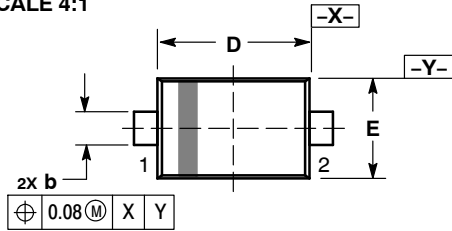
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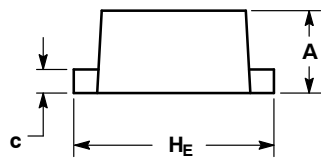
SOD-523
CASE 502-01
ISSUE E

DATE 28 SEP 2010

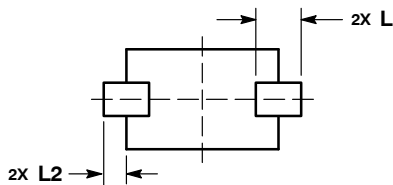
SCALE 4:1



TOP VIEW

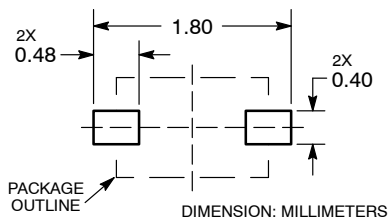


SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



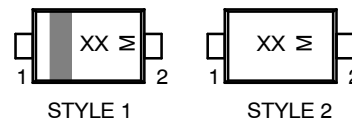
DIMENSION: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN | NOM | MAX |
| A | 0.50 | 0.60 | 0.70 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.07 | 0.14 | 0.20 |
| D | 1.10 | 1.20 | 1.30 |
| E | 0.70 | 0.80 | 0.90 |
| HE | 1.50 | 1.60 | 1.70 |
| L | 0.30 REF | | |
| L2 | 0.15 | 0.20 | 0.25 |

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1: PIN 1. CATHODE (POLARITY BAND)
2. ANODE

STYLE 2: NO POLARITY

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|--------------------|--|
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| DESCRIPTION: | SOD-523 | PAGE 1 OF 1 |

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